

**Notice of References Cited**

Application/Control No.

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Applicant(s)/Patent Under  
Reexamination  
AKRAM, SALMAN

Examiner

David A. Zarneke

Art Unit

2827

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**NON-PATENT DOCUMENTS**

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
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\*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)  
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